

## Patent Abstracts of Japan

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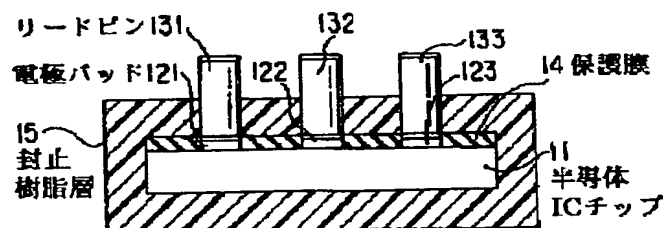
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TITLE : IC PACKAGE AND ITS MANUFACTURE



ABSTRACT : PURPOSE: To provide an IC package which has the size approximate to the IC chip size and facilitates IC mounting, and the manufacturing method of the package.

CONSTITUTION: An IC package 11 is provided with electrode pads 121, 122,... on the surface. A plurality of lead pins 131, 132,... are fixed so as to be connected with the electrode pads 121, 122,..., respectively. A protective film 14 is suitably formed on the surface of the IC chip 11. The whole periphery is sealed with a resin layer 15. The tips of the lead pins 131, 132,... are exposed or protruded from the surface of the resin layer 15. This IC package is manufactured in the following manner: a semiconductor wafer from a wafer process is bonded on a dicing sheet and cut into specified chip types, the dicing sheet is stretched, molds are set between chips, sealing resin solution is potted and cured, and then isolation is performed by the chases.

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